

# ARGOS matrix 200

automated scratch/dig inspection

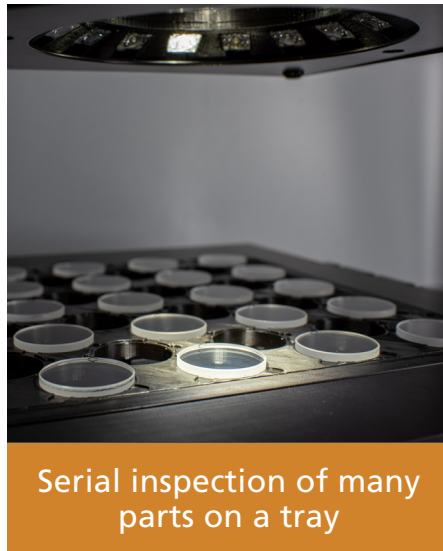
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thinking your optics



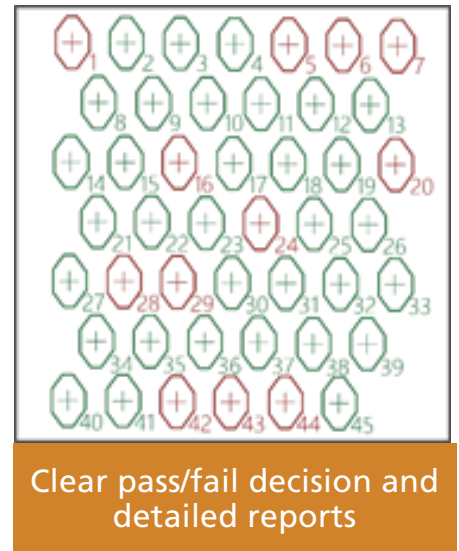
- FULLY AUTOMATED SURFACE INSPECTION
- VERSATILE FROM MICRO-OPTICS TO WAFERS
- OBJECTIVE AND REPRODUCIBLE



Automated stitching of large parts



Serial inspection of many parts on a tray



Clear pass/fail decision and detailed reports

## BENEFITS

**Large flexibility:** any shape from aspheric micro lenses to 8" wafers can be inspected.

**Automated serial inspection without user interaction** reduces cost and improves process quality.

**Objective test results with clear decisions and detailed information** on relevant defects and statistics.

## FUNCTIONALITY

ARGOS matrix 200 is equipped with a high-resolution camera and a switchable dark-field illumination. Images with different lighting configurations are fused for reliable defect detection with high repeatability. A precision 8" stage

allows inspection of large numbers of parts in a tray. Our stitching mode allows inspection of large parts - flat or curved. PDF test reports with clear decision and detailed information are automatically created.

## SPECIFICATIONS

Parameter	ARGOS matrix 200
Nominal resolution (object-side pixel pitch)	2.5 µm
Maximum inspection area	205 × 205 mm
Smallest ISO 10110-7 specification	5/1 × 0.016, L1 × 0.0063, E0.025
Smallest visible defects*	< 1 µm
Precision of size measurement*	< 1.5 µm
Surface material	glass, metal, semiconductors, plastics
Inspection duration	7 min for 8" wafer
System size	ca. 700 × 600 × 600 mm

\*for details see technical specification document